



Printed Circuit Boards  
Interconnection Carriers

**PRINTED CIRCUIT BOARDS**

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4.11.2001

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**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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10 183 FR4 35 L20.35 P10\_06

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

10\_183\_FR4\_35\_L20.35\_p10\_06

Layers	in $\mu$	Material	Build-Up	Assembly		
Layer-1	35 $\mu$	Copper				
	60 $\mu$	Prepreg			(60 $\mu$ PrePreg-Type: 1080)	
	100 $\mu$	Prepreg			(100 $\mu$ PrePreg-Type: 2125)	
Layer-2	35 $\mu$	Copper			A1	
	200 $\mu$	L-FR4				
Layer-3	35 $\mu$	Copper			A2	
	60 $\mu$	Prepreg				
	60 $\mu$	Prepreg				
Layer-4	35 $\mu$	Copper				A2
	200 $\mu$	L-FR4				
Layer-5	35 $\mu$	Copper		A3		
	60 $\mu$	Prepreg				
	60 $\mu$	Prepreg				
Layer-6	35 $\mu$	Copper			A3	
	200 $\mu$	L-FR4				
Layer-7	35 $\mu$	Copper			A4	
	60 $\mu$	Prepreg				
	60 $\mu$	Prepreg				
Layer-8	35 $\mu$	Copper		A4		
	200 $\mu$	L-FR4				
Layer-9	35 $\mu$	Copper		B		
	100 $\mu$	Prepreg				
	60 $\mu$	Prepreg				
Layer-99	35 $\mu$	Copper				

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